

AMENDMENTS TO THE CLAIMS

Claims 1 - 15 (canceled)

16. (previously presented). A carrier reel, comprising:

a hub portion that reels a carrier tape, the carrier tape accommodating a plurality of electronic components therein;

a first accommodating portion, formed in the hub portion; and

a desiccant disposed in the first accommodating portion for protecting the electronic components from moisture.

17. (previously presented) The carrier reel according to claim 16, further comprising:

a flange portion having a first surface and a second surface, the second surface being opposed to and substantially parallel to the first surface, wherein the hub portion is connected between the first and second surfaces.

18. (previously presented) The carrier reel according to claim 17, further comprising:

a bearing portion formed in a center of the hub portion and substantially perpendicular to the first surface or the second surface.

19. (previously presented) The carrier reel according to claim 18, further comprising:

a second accommodating portion, which accommodates a desiccant and is formed in the hub portion, wherein the second accommodating portion is disposed symmetrically with respect to said bearing portion.

20. (previously presented) The carrier reel according to claim 16, wherein the electronic components are semiconductor devices sealed by a resin.

21. (previously presented) The carrier reel according to claim 16, the electronic components are sensitive to humidity.

22. (previously presented) The carrier reel according to claim 16, wherein the hub portion is formed of polystyrene.

23. (previously presented) The carrier reel according to claim 22, wherein the polystyrene includes carbon.

24. (previously presented) The carrier reel according to claim 17, wherein the flange portion is formed of polystyrene.

25. (previously presented) The carrier reel according to claim 24, wherein the polystyrene includes carbon.

26. (currently amended) A carrier reel, comprising:

a winding drum portion, which winds a carrier tape, wherein the carrier tape accommodates a plurality of semiconductor devices therein;
a first accommodating portion, formed in the winding drum portion; and
a drying agent disposed in the first accommodating portion for protecting the ~~electronic components~~ semiconductor devices from moisture.

27. (previously presented) The carrier reel according to claim 26, further comprising:

a pair of flat plates connected with the winding drum portion and arranged in substantially parallel to each other, wherein the winding drum portion is disposed between the flat plates.

28. (previously presented) The carrier reel according to claim 27, further comprising:

a bearing portion formed in a center of the winding drum portion and perpendicular to a surface of the flat plate.

29. (previously amended) The carrier reel according to claim 28, further comprising:

a second accommodating portion formed in the winding drum portion, and further drying agent disposed in the second accommodating portion, wherein the second accommodating portion is disposed symmetrically with respect to said bearing portion.

30. (previously presented) The carrier reel according to claim 26, wherein the electronic component is a semiconductor device sealed by resin.

31. (previously amended) The carrier reel according to claim 26, wherein the electronic component is easily affected by humidity.

32. (previously amended) The carrier reel according to claim 26, wherein the winding drum portion is formed of polystyrene.

33. (previously presented) The carrier reel according to claim 32, wherein the polystyrene includes carbon.

34. (previously amended) The carrier reel according to claim 27, wherein the flat plate is formed of polystyrene.

35. (previously presented) The carrier reel according to claim 34, wherein the polystyrene includes carbon.